

Title (en)

METHOD AND DEVICE FOR THERMAL TREATMENT OF SUBSTRATES

Title (de)

VERFAHREN UND VORRICHTUNG ZUM THERMISCHEN BEHANDELN VON SUBSTRATEN

Title (fr)

PROCEDE ET DISPOSITIF POUR LE TRAITEMENT THERMIQUE DE SUBSTRATS

Publication

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Application

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Abstract (en)

[origin: DE19952017A1] In order to achieve temperature distribution, in particular a homogeneous temperature distribution in, for example, a substrate during a thermal treatment process of said substrate, a method is disclosed for the thermal treatment of substrates, in particular semiconductor wafers, in a process chamber comprising at least one temperature distribution influencing element located in the process chamber. During thermal treatment, the spatial arrangement of the element is altered relative to the substrate and/or to the process chamber. A device for the thermal treatment of substrates in a process chamber is also disclosed, comprising at least one temperature distribution influencing element located in a process chamber wherein a device is provided in order to alter the spatial arrangement of the element relative to the substrate and/or to the process chamber during the thermal treatment process.

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